

**APPARATUS AND METHOD FOR MOUNTING ELECTRONIC COMPONENT**

Patent number: JP11289194 (A)

Publication date: 1999-10-19

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Classification:

- International: H05K13/04; H05K13/04; (IPC1-7): H05K13/04

- European: H05K13/04E

Application number: JP19980093131 19980406

Priority number(s): JP19980093131 19980406

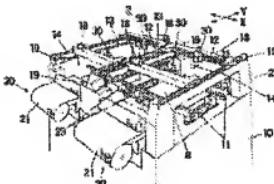
Also published as:

US6588096 (B1)

Abstract of JP 11289194 (A)

**PROBLEM TO BE SOLVED:** To mount electronic components to a substrate with high workability and at a high speed by using a plurality of devices for mounting electronic components and to change the layout flexibly in accordance with the change in the kinds of the substrates.

**SOLUTION:** This apparatus is formed by arranging a plurality of unit devices 2 for mounting electronic components side by side. A conveying route 11 is provided to the center of the upper surface of a base 10, and the device 2 is provided with an XY-table mechanism comprising a feed screw 12 in an X-direction, a feed screw 13 in a Y-direction and motors 18 and 19. A total of four head parts 30 are provided to the respective XY-table mechanisms 21 and 22 to pick up and mount the electronic components of an electronic component supply part 20 to the board. The head part 30 is provided with a plurality of nozzles such as a circle and picks up a plurality of electronic components at the same time and does the recognition of the positions thereof as well.



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